

STM32WL_QFN48_HP_DirectTie_RefBoard

MB1789_HP

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Sheet 1: Project overview (this page)

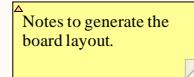
Sheet 2: MB1789_HP.SchDoc

Legend

General comment such as function title, configuration, ...

Text to be added to silkscreen.

Warning text.



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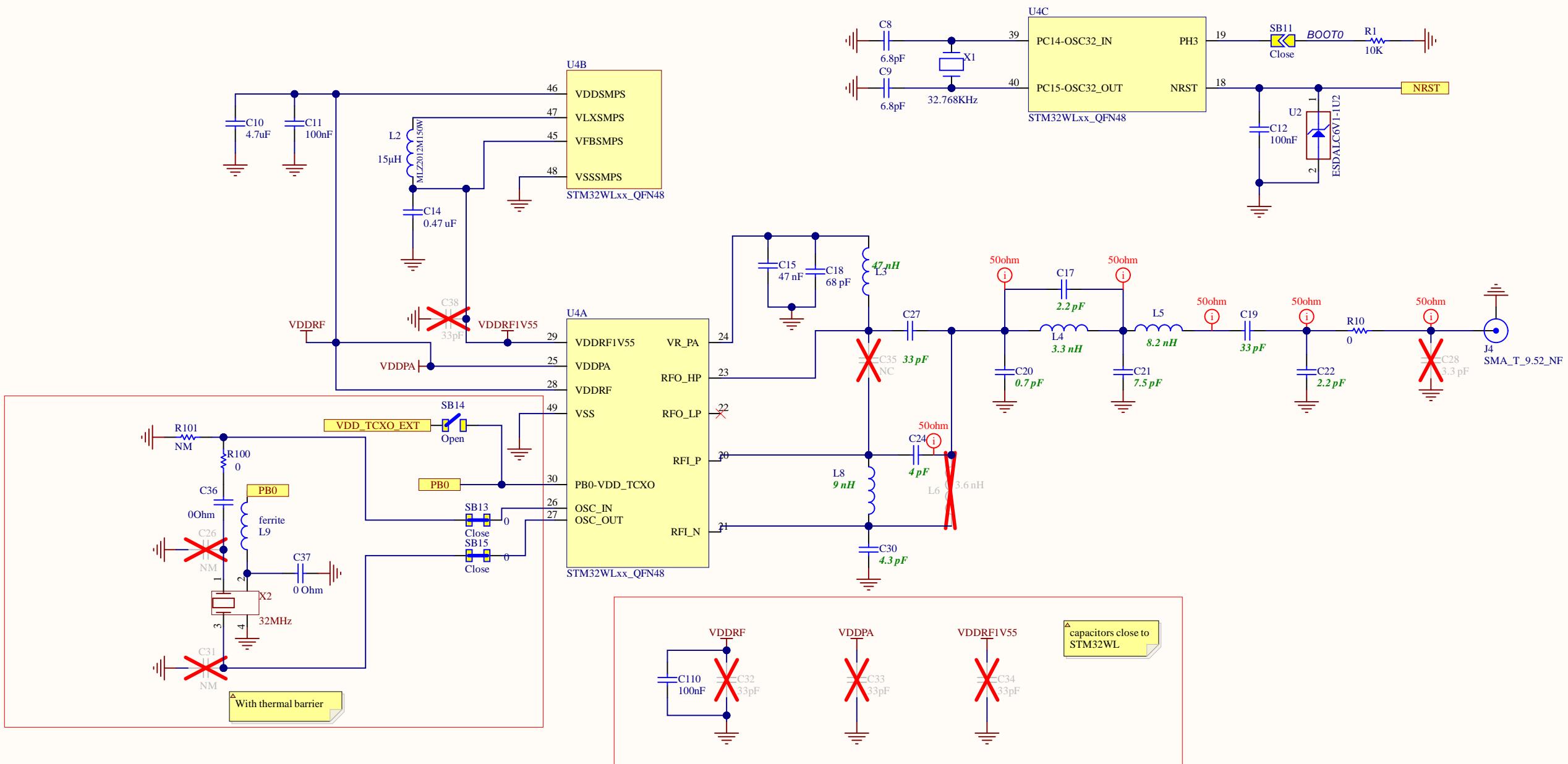
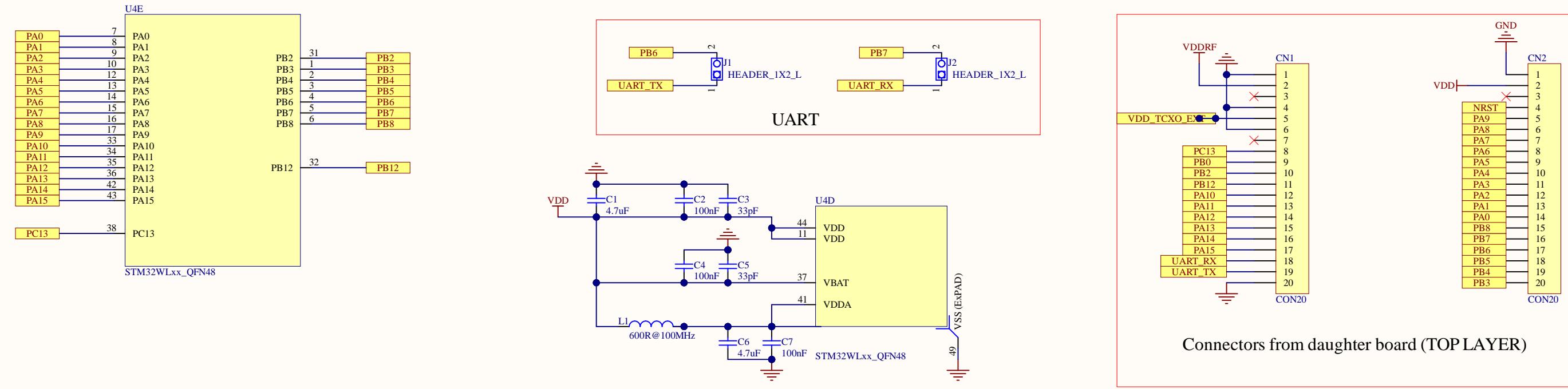
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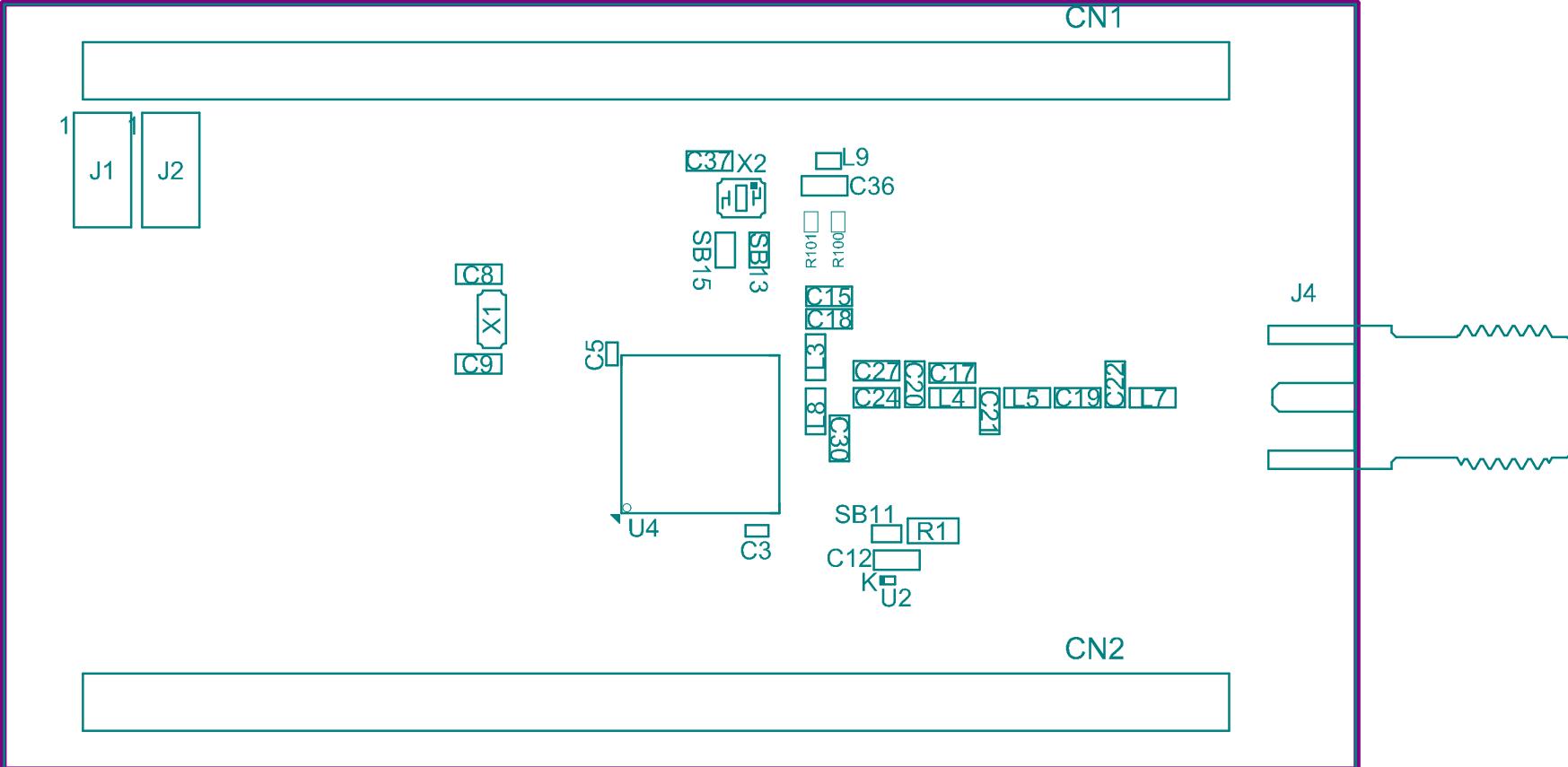
U_Top
MB1789_HP.SchDoc



Title: Schematic sheet title to update	
Project:	STM32WL_QFN48_HP_DirectTie_RefBoard
Variant:	HighBand_HighPower
Revision:	A-01
Size:	A4
Date:	04-04-2022
Reference:	MB1789_HP
Sheet:	1 of 2







Project: STM32WL_QFN48_HP_DirectTie_RefBoard

Layer: Top Assembly

Gerber: .GM14

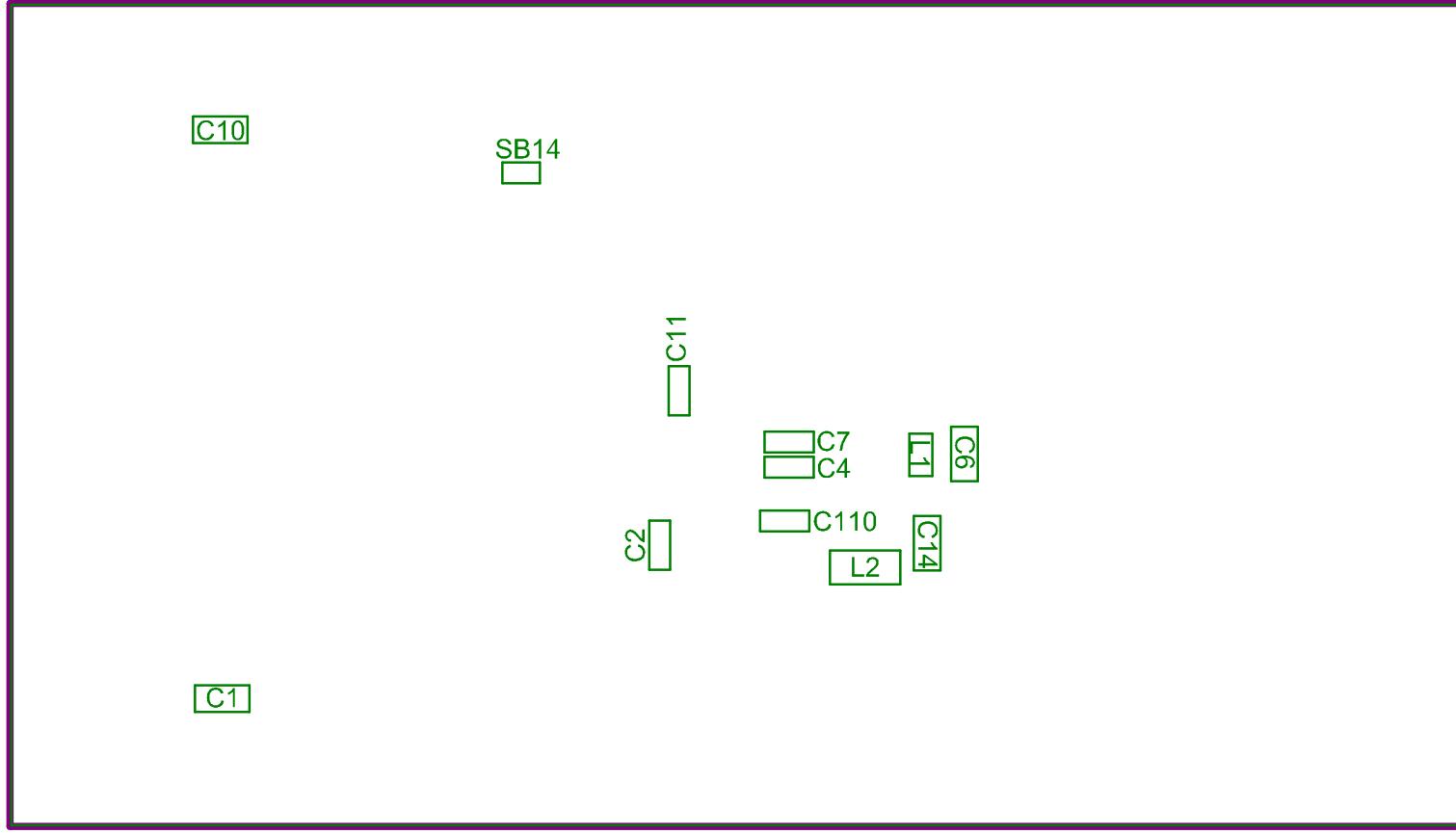
Variant: HighBand_HighPower

Ref: MB1789_HP

Date: 04-04-2022

Rev: A





Project: STM32WL_QFN48_HP_DirectTie_RefBoard

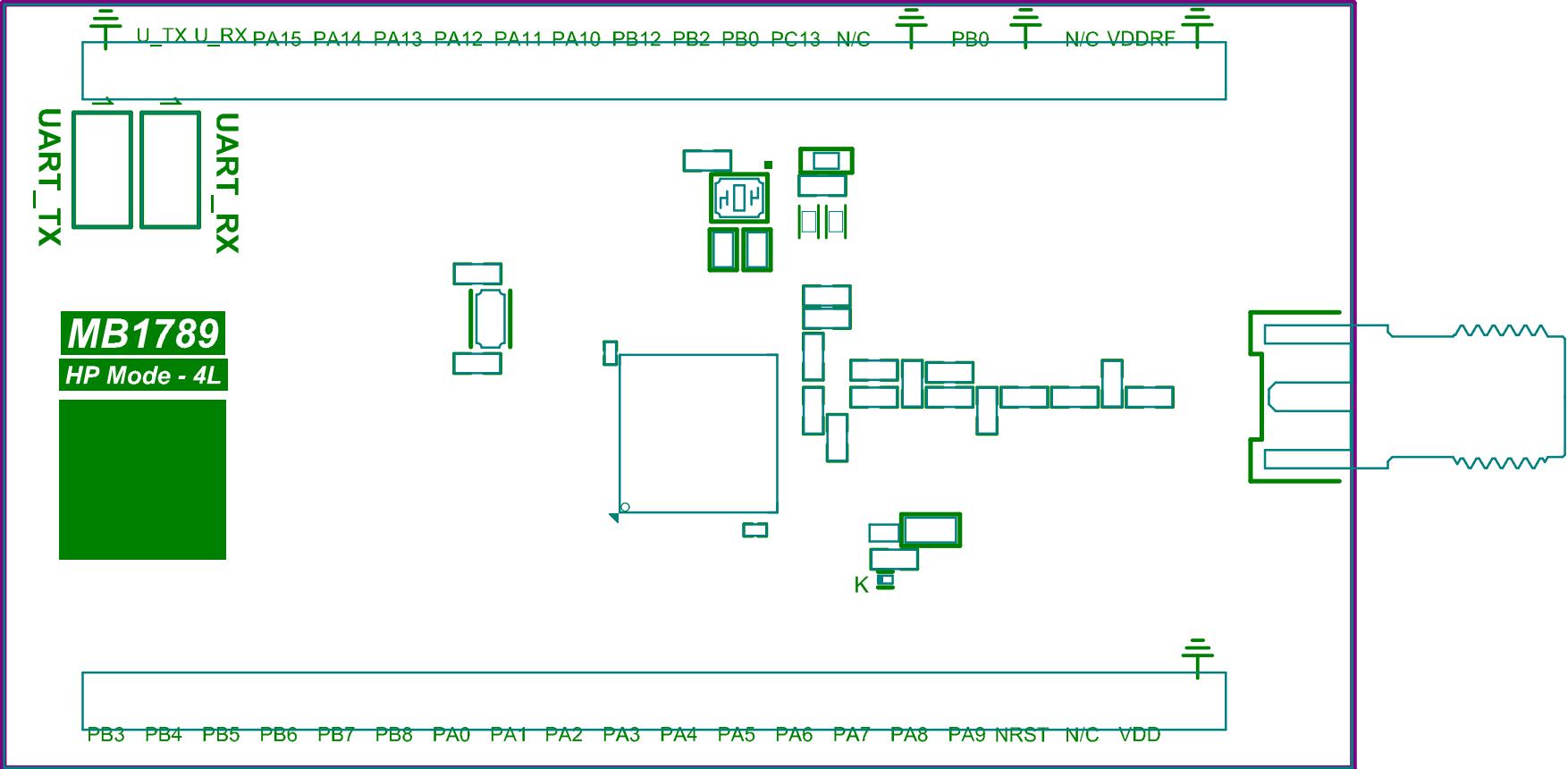
Layer: Bottom Assembly Gerber:.GM15

Variant: HighBand_HighPower Ref: MB1789_HP

Date: 04-04-2022

Rev: A





Top Overlay

.GTO

Bottom Overlay

.GBO

